

one P – A New Dimension of Dispensing: Scheugenpflug System Solutions





What can our modular system offer you?

High flexibility and scalability

Short delivery times

High quality of the individual modules

High future viability



Flexibility is Our Standard

The modular system concept from Scheugenpflug

In the case of dispensing systems there are hardly any "complete off-the-shelf solutions". Rather, the systems must be selected for compatibility with the workpiece and the adhesive, sealant or potting material used. Even factors such as the specific dispensing task, the required cycle time as well as quality requirements and the process environment play an important role in designing the optimal dispensing system. The conflict of interest between superior performance and cost must therefore be solved differently. We solve this problem with modularity.

The basis for your optimal system solution is our modular system consisting of standardized modules. Individual processes can be taken from the modular system and combined according to your individual requirements – while maintaining the standard. For instance our dispensing cell concept, which is based on many different material preparation and feeding units, dispensers, axis systems, operating concepts and control units in scalable enclosures, provides the best fit at series production prices. The same approach is used for manual work stations and is linked to the production environment when using special integration systems.

If your production changes, our systems flexibly change with it. The systems can handle it all: different materials, larger production quantities, faster cycle times, higher quality requirements, more process reliability, etc. You define what you need and we configure the best system for you. Further enhancements are continually incorporated in our solutions. You decide the point at which adding an extension is worthwhile to you. However, with each modification of your modules, they will remain "state of the art".

one P – A New Dimension of Dispensing

With our high-performance system solution for self-leveling media, you can take your dispensing process to a new level!



Let's talk about your project: +49 9445 9564 ext. 0, vertrieb.de@scheugenpflug.de

Perfect for your application

With our new system solution, numerous different dispensing tasks can be realized – individually tailored to your requirements and in top quality.

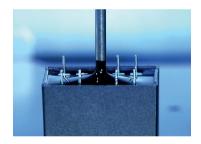
Adhesive bonding

The complexity of adhesive bonding processes is often underestimated. To make sure that effective, lasting adhesive bonds can be achieved, the upstream and downstream process steps also need to be taken into account in addition to material application and the subsequent joining process only. Hybrid processes, in which bonding is supplemented by a further function such as sealing or heat dissipation, are becoming increasingly important.





Info: Learn more about adhesive bonding www.scheugenpflug.de/en/adhesive-bonding



Potting

Depending on the geometry of the component or the properties of the potting material, the filling process must be carried out in different ways. The medium can be potted in one go, simultaneously at several points or with interruptions. A further variant is the "Dam and Fill" or "Frame and Fill", in which a sealing bead (the dam or frame) is applied as a contour first and the inner area is then filled with another potting material.



Info: Learn more about potting www.scheugenpflug.de/en/potting

Sealing

In this process, sensitive electronic surfaces are coated with a very thin layer of potting resin or protective varnish. For effective protection, it is essential to thoroughly coat the surface, including electrical contacts, soldered connections and other surface structures. Low-viscosity potting materials are therefore used in this process.



Info: Learn more about sealing www.scheugenpflug.de/en/conformal-coating



